

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6653894

SUBMISSION TYPE:	RESUBMISSION
NATURE OF CONVEYANCE:	ASSIGNMENT
RESUBMIT DOCUMENT ID:	506428124

CONVEYING PARTY DATA

Name	Execution Date
YOSHIAKI FUKUZUMI	12/04/2020
JUN FUJIKI	12/07/2020
MATTHEW J. KING	11/17/2020
SIDHARTHA GUPTA	11/11/2020
PAOLO TESSARIOL	12/17/2020
KUNAL SHROTRI	12/03/2020
KYE HYUN BAEK	12/03/2020
KYLE A. RITTER	04/09/2021
SHUJI TANAKA	12/04/2020
UMBERTO MARIA MEOTTO	11/18/2020
RICHARD J. HILL	12/10/2020
MATTHEW HOLLAND	11/17/2020

RECEIVING PARTY DATA

Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY
Internal Address:	MAILSTOP 1-507
City:	BOISE
State/Country:	IDAHO
Postal Code:	83707-0006

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17127971

CORRESPONDENCE DATA

Fax Number: (801)531-9168

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Address Line 1: P.O. BOX 2550
Address Line 4: SALT LAKE CITY, UTAH 84110

ATTORNEY DOCKET NUMBER: 2269-15865(2020-0402.00)

NAME OF SUBMITTER: DANIEL J. BEZDJIAN

SIGNATURE: /Daniel J. Bezdjian/

DATE SIGNED: 04/13/2021

Total Attachments: 27

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source=2021-04-13-Assignment-15865US#page9.tif
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source=2021-04-13-Assignment-15865US#page17.tif
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ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, each undersigned ASSIGNOR does hereby:

SELL, ASSIGN AND TRANSFER to MICRON TECHNOLOGY, INC. (“ASSIGNEE”), a corporation of the State of Delaware, having a place of business at 8000 South Federal Way, Mailstop 1-507, Boise, ID 83707-0006, the entire right, title and interest for the United States and all foreign countries in and to any and all improvements that are disclosed in the **Application for United States Letters Patent** that has been executed by each undersigned ASSIGNOR concurrently herewith, and titled **MICROELECTRONIC DEVICES INCLUDING TIERED STACKS INCLUDING CONDUCTIVE STRUCTURES ISOLATED BY SLOT STRUCTURES, AND RELATED ELECTRONIC SYSTEMS AND METHODS**, such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent or the legal equivalent thereof that have been or may be filed in the United States and all foreign countries relating to any of such improvements; all original, reexamined and reissued patents that have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application made in the United States;

AUTHORIZE the ASSIGNEE to apply for and receive any and all United States and foreign patents relating to such improvements in its own name;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to and in the name of the ASSIGNEE;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement or encumbrance affecting the rights and property herein conveyed has been or will be made or entered into by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT, when requested and at the expense of the ASSIGNEE, to carry out in good faith the intent and purpose of this Assignment, to execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications relating to any and all such improvements; to execute all rightful oaths, declarations, assignments, powers of attorney and other papers; to communicate to the ASSIGNEE all facts and provide to the ASSIGNEE all documents and things known and accessible to the undersigned relating to such improvements and the history thereof, and testify as to the same in any interference, litigation or other proceeding relating thereto; and generally to do everything possible that the ASSIGNEE shall consider desirable for vesting title to such improvements in the ASSIGNEE, and to secure, maintain, defend and enforce valid and enforceable patent protection for such improvements;

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ASSIGNOR(S):

Yoshiaki Fukuzumi Dec. 4, 2020
Yoshiaki Fukuzumi
Mailing address: 5-15-22 Bessho Minami-ku, Yokohama, Kanagawa 2320064 Japan

Jun Fujiki Date: Dec 7, 2020
Jun Fujiki
Mailing address: c/o Micron Memory Japan, G.K., 8th floor, Shinagawa Season Terrace, 1-2-70, Konan, Minato-ku, Tokyo 108-0075 Japan

Matthew J. King Date: _____
Mailing address: 6272 North Stafford Place, Boise, ID 83713

Sidhartha Gupta Date: _____
Mailing address: 2963 S Shadywood Way, Boise, ID 83716

Paolo Tessariol Date: _____
Mailing address: Via C. Tolomeo 5, Arcore 20862 Italy

Kunal Shrotri
Mailing address: 1472 E Spinnaker Ct, Boise, ID 83706

Date: _____

Kye Hyun Baek
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Date: _____

Kyle A. Ritter
Mailing address: 6708 East Bend Ridge Street, Boise, ID 83716

Date: _____

Shuji Tanaka

Shuji Tanaka
Mailing address: 8th floor, Shinagawa Season Terrace, 1-2-70, Konan, Minato-ku, Tokyo 108-0075
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Date: *4 Dec, 2020*

Umberto Maria Meotto
Mailing address: Via alle Fontane 31/9, Rivoli 10098 Italy

Date: _____

Richard J. Hill
Mailing address: 636 N Morningside Way, Boise, ID 83712

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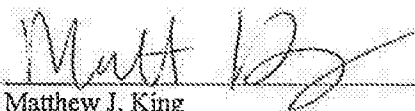
Yoshiaki Fukuzumi

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Mailing address: c/o Micron Memory Japan, G.K., 8th floor, Shinagawa Season Terrace, 1-2-70, Konan, Minato-ku, Tokyo 108-0075 Japan



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Date: 11 Nov 2020

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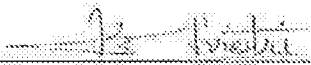
Date: _____
Yoshiaki Fukuzumi
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Shuji Tanaka
Mailing address: 8th floor, Shinagawa Season Terrace, 1-2-70, Konan, Minato-ku, Tokyo 108-0075
Japan

Date:

.....
Umberto Maria Meotto
Mailing address: Via alle Fontane 31/9, Rivoli 10098 Italy

Date:

.....
Richard J. Hill
Mailing address: 636 N Morningside Way, Boise, ID 83712

Date:


.....
Matthew Holland
Mailing address: 6215 East Grand Prairie Drive, Boise, ID 83716

Date: 11/17/2020

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, each undersigned ASSIGNOR does hereby:

SELL, ASSIGN AND TRANSFER to MICRON TECHNOLOGY, INC. ("ASSIGNEE"), a corporation of the State of Delaware, having a place of business at 8000 South Federal Way, Mailstop 1-507, Boise, ID 83707-0006, the entire right, title and interest for the United States and all foreign countries in and to any and all improvements that are disclosed in the **Application for United States Letters Patent Serial No. 17/127,971 filed on December 18, 2020, and titled MICROELECTRONIC DEVICES INCLUDING TIERED STACKS INCLUDING CONDUCTIVE STRUCTURES ISOLATED BY SLOT STRUCTURES, AND RELATED ELECTRONIC SYSTEMS AND METHODS**, such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent or the legal equivalent thereof that have been or may be filed in the United States and all foreign countries relating to any of such improvements; all original, reexamined and reissued patents that have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application made in the United States;

AUTHORIZE the ASSIGNEE to apply for and receive any and all United States and foreign patents relating to such improvements in its own name;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to and in the name of the ASSIGNEE;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement or encumbrance adversely affecting the ASSIGNEE'S rights, title, and interest to the rights and property herein conveyed has been or will be made or entered into by the undersigned, and that the undersigned has the full right to convey the same as herein expressed to the ASSIGNEE;

COVENANT, when requested and at the expense of the ASSIGNEE, to carry out in good faith the intent and purpose of this Assignment, to execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications relating to any and all such improvements; to execute all rightful oaths, declarations, assignments, powers of attorney and other papers; to communicate to the ASSIGNEE all facts and provide to the ASSIGNEE all documents and things known and accessible to the undersigned relating to such improvements and the history thereof, and testify as to the same in any interference, litigation or other proceeding relating thereto; and generally to do everything possible that the ASSIGNEE shall consider desirable for vesting title to such improvements in the ASSIGNEE, and to secure, maintain, defend and enforce valid and enforceable patent protection for such improvements;

AGREE AND ACKNOWLEDGE that the SALE, ASSIGNMENT AND TRANSFER of rights and property set forth herein is and shall be IRREVOCABLE and BINDING upon the heirs, assigns, representatives and successors of each undersigned ASSIGNOR and EXTEND to the successors, assigns and nominees of the ASSIGNEE.

ASSIGNOR(S):

Date: _____
Yoshiaki Fukuzumi
Mailing address: 5-15-22 Bessho Minami-ku, Yokohama, Kanagawa 2320064 JAPAN

Date: _____
Jun Fujiki
Mailing address: c/o Micron Memory Japan, G.K., 8th floor, Shinagawa Season Terrace, 1-2-70, Konan, Minato-ku, Tokyo 108-0075 Japan

Date: _____
Matthew J. King
Mailing address: 6272 North Stafford Place, Boise, ID 83713

Date: _____
Sidhartha Gupta
Mailing address: 2963 S Shadywood Way, Boise, ID 83716


Date: _____
Paolo Tessariol
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Kunal Shrotri
Mailing address: 1472 E Spinnaker Ct, Boise, ID 83706

Date: _____

Kye Hyun Baek
Mailing address: 7102 E Highland Valley RD, Boise, ID 83716

Date: _____



Kyle A. Ritter
Mailing address: 6708 East Bend Ridge Street, Boise, ID 83716

Date: 4/9/21

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Mailing address: 5-15-22 Bessho Minami-ku, Yokohama, Kanagawa 2320064 Japan

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